The Phoenix Advanced Microelectronics Center (AMC), a DMEA-accredited facility for design, assembly, test and broker services, delivers a trusted and assured chain of custody, processing ITAR and classified work for sensitive military programs. It is home to innovative 3D packaging technology for developing secure and size, weight and power (SWaP)-optimized memory, storage and custom microelectronic solutions. Now with expanded 2.5D heterogeneous integration capabilities, equipment and processes, Mercury can deliver the first open systems architecture processing solutions at chip-scale. This approach using an interposer and customizable chiplets joined with high-density interconnects creates agile, easily upgradable system in package (SiP) devices to accelerate processing at the “edge”, i.e. closer to the antenna or sensor.

Our trusted center of excellence with advanced design and manufacturing capabilities provides the Department of Defense with a trusted supply chain partner creating secure processing solutions designed, built and supported in the U.S.A.

- World-class 115,000 sq. ft. facility with new 2,092 sq. ft. ISO-8 class 100K clean room and 2843 sq. ft. ISO-7 class 10K clean room
- AS9100 and ISO 9001:2008 certified
- DMEA trusted foundry program accredited
- Classified test area
- Counterfeit parts prevention process
- Vetted and cleared personnel

Cultivating the breadth of engineers working in a cutting-edge facility on world-class processing platforms, we are investing in the future of innovation in the Phoenix region. Once fully operational, this new capability is expected to add approximately 50 new jobs in engineering and manufacturing.